



Product Change Notification / RMES-01 SIDA906

Date:

04-Mar-2022

Product Category:

Ethernet PHYs, Ethernet Switches, PCIe - Signal Integrity

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3740.006 Final Notice: Qualification of MTAI as an additional final test site for selected VSC751x, VSC33xx and VSC82xx device families available in various packages.

Affected CPNs:

[RMES-01 SIDA906_Affected_CPN_03042022.pdf](#)
[RMES-01 SIDA906_Affected_CPN_03042022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of MTAI as an additional final test site for selected VSC751x, VSC33xx and VSC82xx device families available in various packages.

Pre and Post Change Summary:

	Pre-Change	Post Change	
Final Test Site	ASE Test (ASE9)	ASE Test (ASE9)	Microchip Technology

			Thailand (MTAI)
Base Quantity Multiple (BQM)	No BQM change Refer to Pre and Post change comparison		
Tray Stacking	No Tray Stacking change Refer to Pre and Post change comparison		
Pin 1 Orientation	Chamfer Side Refer to Pre and Post change comparison		
Tray Drawing / Dimension	No Tray Drawing / Dimension change Refer to Pre and Post change comparison		

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying MTAI as an additional final test site.

Change Implementation Status:In Progress

Estimated First Ship Date:April 10, 2022 (date code: 2216)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2022					April 2022			
Workweek	10	11	12	13	14	15	16	17	18
Qual Report Availability	x								
Final PCN Issue Date	x								
Estimated Implementation Date							x		

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

March 04, 2022: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_RMES-01SIDA906_Pre and Post Change Summary.pdf](#)
[PCN_RMES-01SIDA906_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

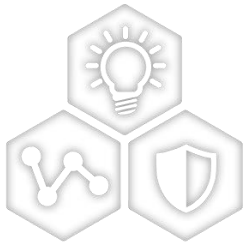
Affected Catalog Part Numbers (CPN)

VSC7513XKS
VSC7514XKS
VSC3308YKU
VSC3340YJJ-01
VSC3340YJJ-31
VSC8211XVW
VSC8221XHH
VSC8224XHG
VSC8244XHG

CCB 3740.006
Pre and Post Change Summary
PCN #: RMES-01SIDA906



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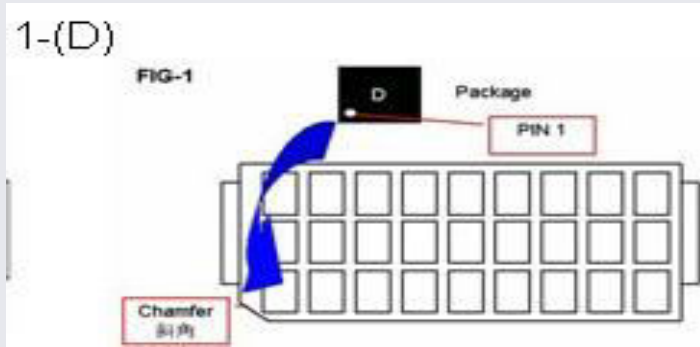
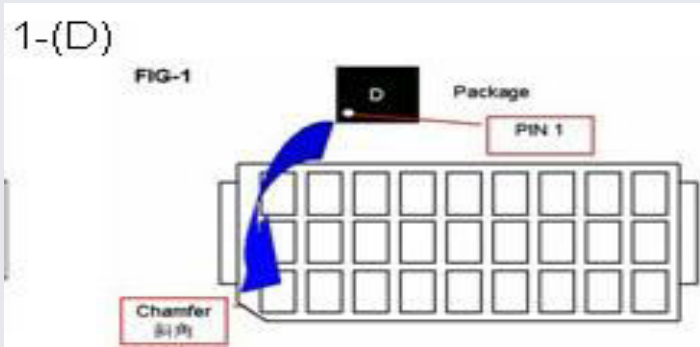


SMART | CONNECTED | SECURE

List of Catalog Part Numbers

Catalog Part Number
VSC7513XKS
VSC7514XKS
VSC3308YKU
VSC3340YJJ-01
VSC3340YJJ-31
VSC8211XVW
VSC8221XHH
VSC8224XHG
VSC8244XHG

Pre and Post Change Summary – Pin 1 Orientation

	ASE9	MTAI
Final Test Location	ASE Test (ASE9)	Microchip Technology Thailand (MTAI)
Pin 1 Orientation	 <p>1-(D) FIG-1 Package PIN 1 Chamfer 倒角</p> <p>Near Chamfer side</p>	 <p>1-(D) FIG-1 Package PIN 1 Chamfer 倒角</p> <p>Near Chamfer side</p>

Pre and Post Change Summary – BQM / Tray Stacking per Package

Item	Package	Packing Media Type	ASE9		MTAI	
			BQM	Tray Stack	BQM	Tray Stack
1	PBGA 256L 17x17mm	TRAY	90	5+1	90	5+1
2	FCCSP-FC 69L 10x10mm	TRAY	184	5+1	184	5+1
3	HFCBGA-HS 484L 23x23mm	TRAY	60	5+1	60	5+1
4	LBGA 117L 14x10mm	TRAY	154	5+1	154	5+1
5	TFBGA 100L 9x9x1.4mm	TRAY	260	5+1	260	5+1
6	HSBGA-HS 260L 19x19mm	TRAY	84	5+1	84	5+1

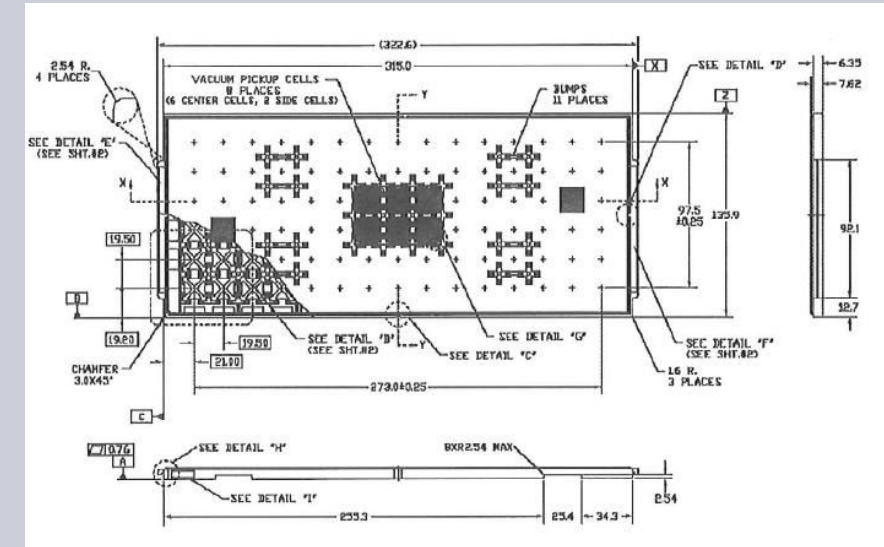
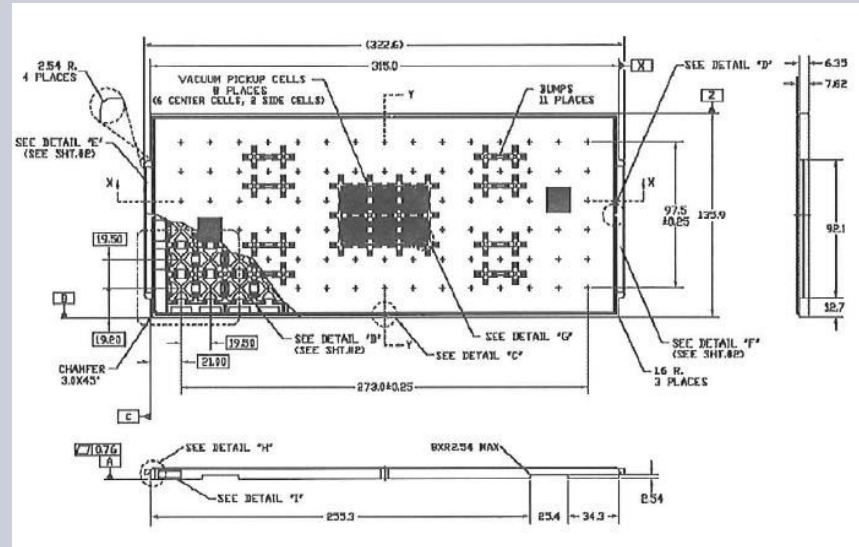
Note: No changes in Base Quantity Multiple (BQM) and Tray Stacking

Tray Drawing - PBGA 256L 17x17mm MSL-4

ASE9

MTAI

Tray Comparison



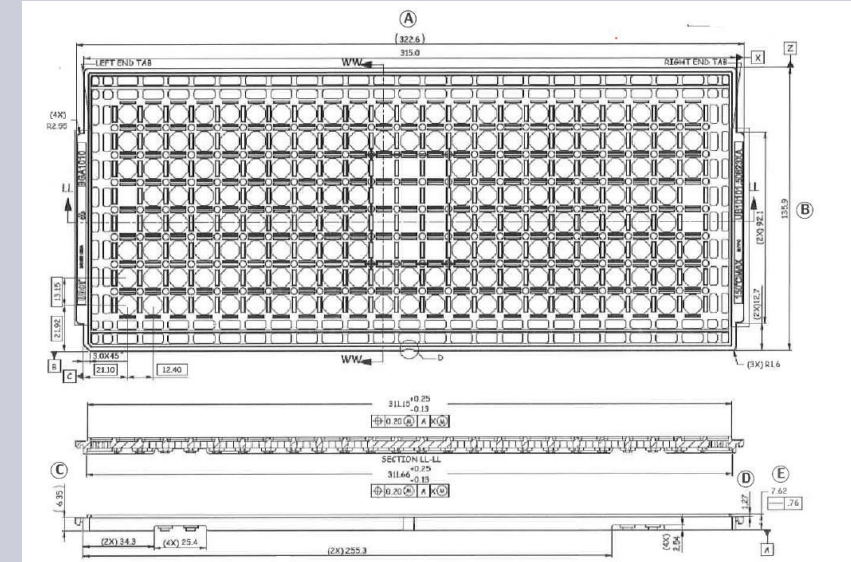
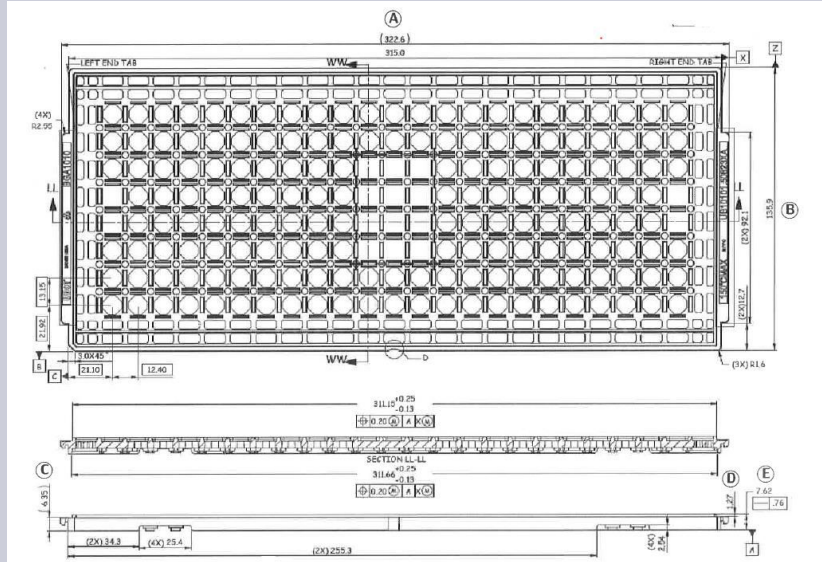
Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Color
MTAI	150C	6	15	90	Black
ASE9	150C	6	15	90	Black

Tray Drawing - FCCSP-FC 69L 10x10mm MSL-4

ASE9

MTAI

Tray Comparison



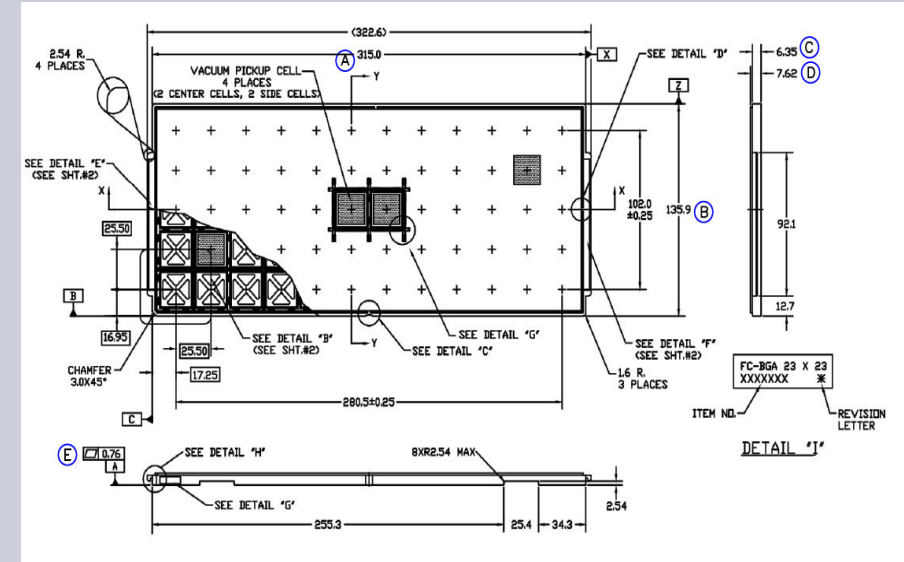
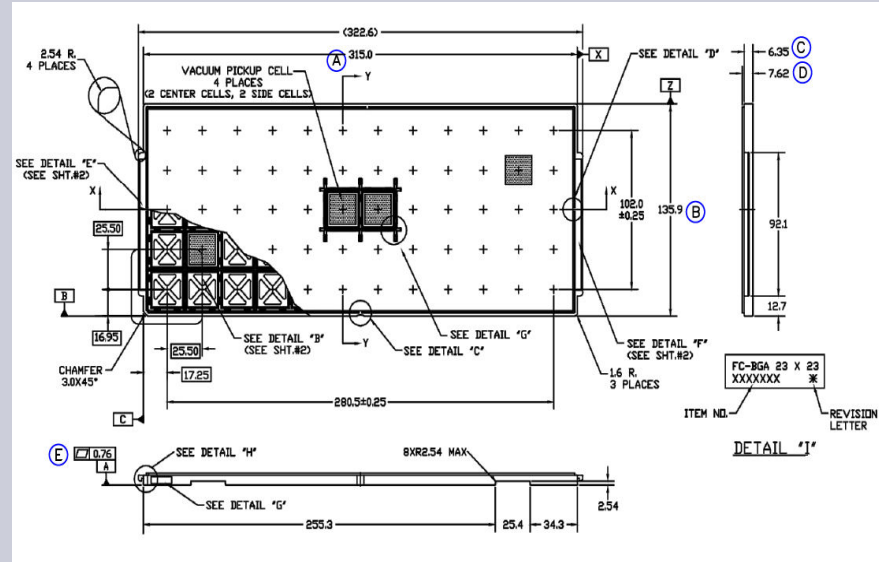
Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Color
MTAI	150C	8	23	184	Black
ASE9	150C	8	23	184	Black

Tray Drawing - HFCBGA-HS 484L 23x23mm MSL-4

ASE9

MTAI

Tray Comparison



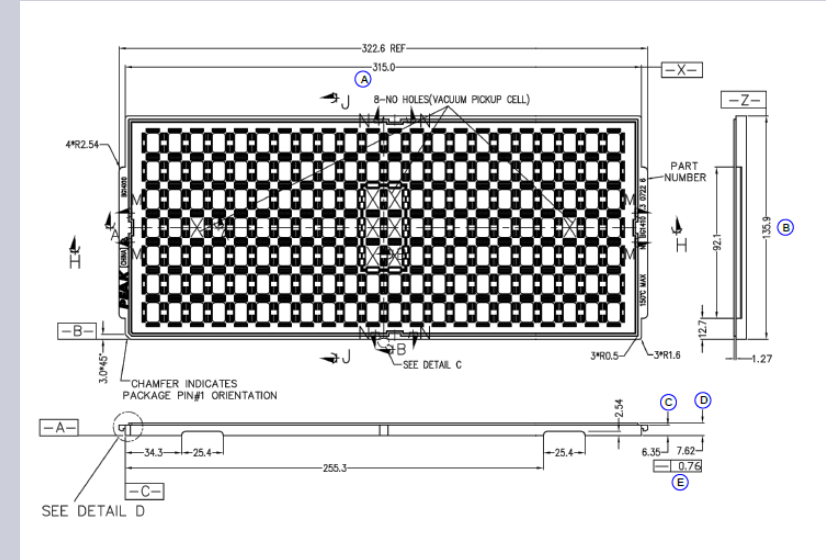
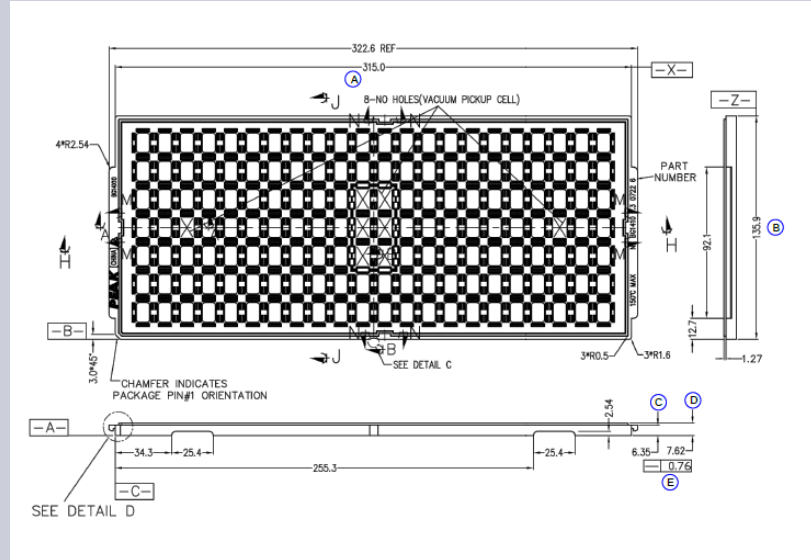
Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Color
MTAI	150C	5	12	60	Black
ASE9	150C	5	12	60	Black

Tray Drawing - LBGA 117L 14x10mm MSL-3

ASE9

MTAI

Tray Comparison



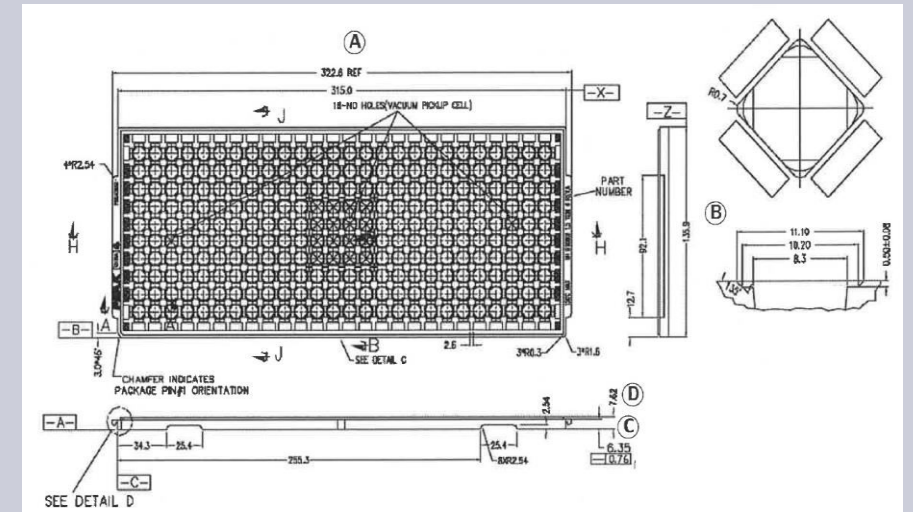
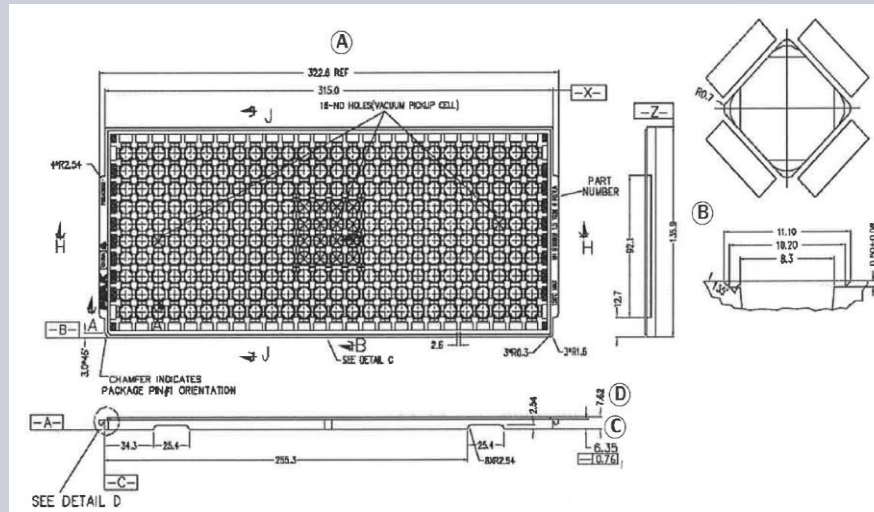
Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Color
MTA1	150C	7	22	154	Black
ASE9	150C	7	22	154	Black

Tray Drawing - TFBGA 100L 9x9x1.4mm MSL-3

ASE9

MTAI

Tray Comparison



Plant	Bakeable (Temp C)	Row	Col	Unit per Tray	Color
MTAI	150C	10	26	260	Black
ASE9	150C	10	26	260	Black



QUALIFICATION REPORT SUMMARY

PCN #: RMES-01SIDA906

**Date:
February 16, 2022**

Qualification of MTAI as an additional final test site for selected VSC751x, VSC33xx and VSC82xx device families available in various packages.

Purpose: Qualification of MTAI as an additional final test site for selected VSC751x, VSC33xx and VSC82xx device families available in various packages.

CCB No.: 3740.006

Test Name	Test Conditions	Result / Remarks
Test Comparison	<ul style="list-style-type: none">• Select 50 good sample - test using the original platform and retest using destination platform.	PASSED
Lot Verification	<ul style="list-style-type: none">• Select 1 fresh lot.• Lot quantity is 3,000 units.• Test using the new test location platform. Then cross correlate with original test location platform.	PASSED